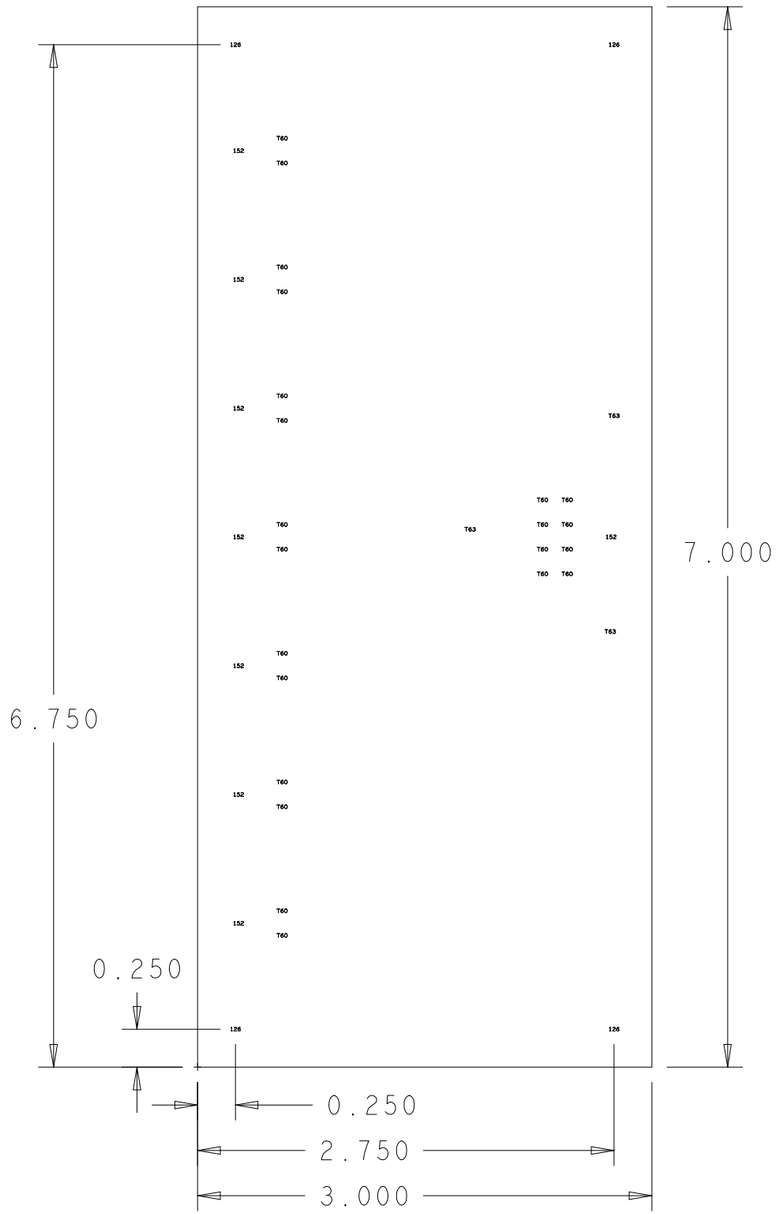
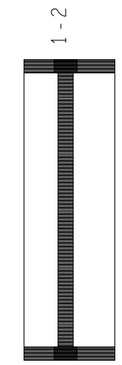


DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
T60	60.0	PLATED	22
T63	63.0	PLATED	3
126	126.0	PLATED	4
152	152.0	NON-PLATED	8

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED



L1: TOP CONDUCTOR - COPPER 2.7 MIL

* DIELECTRIC - FR-4 56.6 MIL

L2: BOTTOM CONDUCTOR - COPPER 2.7 MIL

DESIGN CROSS SECTION CHART
TOTAL THICKNESS 62 MIL

CLASS II FABRICATION NOTES: (UNLESS OTHERWISE SPECIFIED)

1. BOARDS SHALL BE 100% NET LIST TESTED FOR OPENS AND SHORTS PER PROVIDED IPC-D-356 NETLIST.
2. THIS BOARD SHALL BE MANUFACTURED IN ACCORDANCE WITH IPC-6012A CLASS II SPECIFICATIONS AND MEET IPC-600 CLASS II ACCEPTABILITY STANDARDS.
3. MATERIAL:
   a. FR4 PER IPC 4101B/24,/26, OR /28.
   b. SIGNAL LAYERS TO BE 2 OZ. COPPER.
   ~~c. PLANE LAYERS TO BE 1 OZ. COPPER.~~
   d. OVERALL THICKNESS TO BE 0.062" +/- 10%
4. LEGEND:
   a. WHITE NON-CONDUCTIVE EPOXY INK TOP SIDE.
5. SOLDERMASK:
   a. APPLY LIQUID PHOTO-IMAGABLE (LPI) SOLDER MASK OVER BARE COPPER PER IPC-SM-840 CLASS H, COLOR VIOLET, BOTH SIDES.
6. PLATING FINISH:
   a. HOT AIR SOLDER LEVELING (HASL) SN63A SnPb SOLDER.
   ~~b. IMMERSION SILVER (Ag).~~
7. PROCESS ALLOWANCES:
   a. MAXIMUM BOW AND TWIST ACROSS DIAGONAL CORNERS OF THE BOARD SHALL NOT EXCEED 0.75%.
   b. HOLE DIMENSIONS APPLY AFTER PLATING.
   c. ALL HOLES SHALL BE LOCATED WITHIN 0.003" DIAMETER OF TRUE POSITION.
   d. LAYER TO LAYER REGISTRATION SHALL BE WITHIN 0.003".
   e. CONDUCTOR WIDTHS AND SPACING SHALL BE WITHIN +/- 0.002".
   f. REMOVE ALL BURRS AND BREAK SHARP EDGES 0/015" MAX.
   g. CUT OUTSIDE OF 0.001" BOARD OUTLINE.

UNLESS OTHERWISE SPECIFIED	SIGNATURES	DATE	CCE BATTERY SPHERE PCB		
DIMENSIONS ARE IN INCHES TOLERANCES ON: 2 PL DECIMALS +/- 0.02" 3 PL DECIMALS +/- 0.005" ANGLES +/- 1 Degree FRACTIONS +			MONTEREY BAY AQUARIUM RESEARCH INSTITUTE 7700 SANDHOLDT ROAD MOSS LANDING, CA		
	DESIGNED BY: MARK CHAFFEY		SIZE B	RELEASE A	DWG NO 11021186-07
	LAYOUT BY: JOSE ROSAL		SCALE 1-1		SHEET 1-1